

Leila Ladani

List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

80
papers

1,265
citations

20
h-index

32
g-index

87
ext. papers

1,525
ext. citations

3
avg, IF

5.48
L-index

#	Paper	IF	Citations
80	Grain Scale Investigation of the Mechanical Anisotropic Behavior of Electron Beam Powder Bed Additively Manufactured Ti6Al4V Parts. <i>Metals</i> , 2022 , 12, 163	2.3	0
79	Process Parameter Optimization in Metal Laser-Based Powder Bed Fusion Using Image Processing and Statistical Analyses. <i>Metals</i> , 2022 , 12, 87	2.3	3
78	Finite Element Modeling of Quantitative Ultrasound Analysis of the Surgical Margin of Breast Tumor.. <i>Tomography</i> , 2022 , 8, 570-584	3.1	1
77	Finite Element Analysis of Identifying Breast Cancer Tumor Grades Through Frequency Spectral Variation of High-Frequency Ultrasound 2022 , 1, 100003		
76	Location-dependent deformation behavior of additively manufactured copper and copper-carbon nanotube composite. <i>Journal of Alloys and Compounds</i> , 2022 , 909, 164800	5.7	
75	Mechanical Behavior of Electron Beam Powder Bed Fusion Additively Manufactured Ti6Al4V Parts at Elevated Temperatures. <i>Journal of Manufacturing Science and Engineering, Transactions of the ASME</i> , 2021 , 143,	3.3	8
74	Computational Modeling of Ultrasound C-Scan Imaging Using Transmitted Signal Peak Density. <i>Applied Sciences (Switzerland)</i> , 2021 , 11, 4924	2.6	2
73	Defect analysis and fatigue strength prediction of as-built Ti6Al4V parts, produced using electron beam melting (EBM) AM technology. <i>Materialia</i> , 2021 , 16, 101041	3.2	8
72	Applications of artificial intelligence and machine learning in metal additive manufacturing. <i>JPhys Materials</i> , 2021 , 4, 042009	4.2	2
71	Review of Powder Bed Fusion Additive Manufacturing for Metals. <i>Metals</i> , 2021 , 11, 1391	2.3	12
70	Towards developing multiscale-multiphysics models and their surrogates for digital twins of metal additive manufacturing. <i>Additive Manufacturing</i> , 2021 , 46, 102089	6.1	12
69	Mechanical Anisotropy and Surface Roughness in Additively Manufactured Parts Fabricated by Stereolithography (SLA) Using Statistical Analysis. <i>Materials</i> , 2020 , 13,	3.5	8
68	Temperature Profile, Bead Geometry, and Elemental Evaporation in Laser Powder Bed Fusion Additive Manufacturing Process. <i>Jom</i> , 2020 , 72, 429-439	2.1	20
67	Development of High-Temperature-Resistant Seed Layer for Electrodeposition of Copper for Microelectronic Applications. <i>Journal of Electronic Materials</i> , 2020 , 49, 1387-1395	1.9	4
66	Experimental measurement of thermal diffusivity, conductivity and specific heat capacity of metallic powders at room and high temperatures. <i>Powder Technology</i> , 2020 , 374, 648-657	5.2	8
65	Relationship between peak density and acoustic scattering in high-frequency ultrasound wave propagation. <i>SN Applied Sciences</i> , 2020 , 2, 1	1.8	5
64	Laser Interaction with Surface in Powder Bed Melting Process and Its Impact on Temperature Profile, Bead and Melt Pool Geometry. <i>Minerals, Metals and Materials Series</i> , 2019 , 319-329	0.3	1

63	High-Frequency Ultrasound Analysis in Both Experimental and Computation Level to Understand the Microstructural Change in Soft Tissues. <i>Minerals, Metals and Materials Series</i> , 2019 , 87-97	0.3	1
62	The Potential for Metal/Carbon Nanotubes Composites as Interconnects. <i>Journal of Electronic Materials</i> , 2019 , 48, 92-98	1.9	10
61	Examination of a spectral-based ultrasonic analysis method for materials characterization and evaluation. <i>Biomedical Signal Processing and Control</i> , 2018 , 40, 454-461	4.9	6
60	Direct metal laser melting of Inconel 718: Process impact on grain formation and orientation. <i>Journal of Alloys and Compounds</i> , 2018 , 736, 297-305	5.7	48
59	Multi-Physics Modeling of Laser Interaction With Surface in Powder Bed Melting Process 2018 ,		2
58	Influence of Microstructure on the High-Frequency Ultrasound Measurement of Peak Density. <i>Journal of Nondestructive Evaluation, Diagnostics and Prognostics of Engineering Systems</i> , 2018 , 1,	0.9	2
57	Fabrication of carbon nanotube/copper and carbon nanofiber/copper composites for microelectronics. <i>Materials Today Communications</i> , 2017 , 11, 123-131	2.5	16
56	Effective liquid conductivity for improved simulation of thermal transport in laser beam melting powder bed technology. <i>Additive Manufacturing</i> , 2017 , 14, 13-23	6.1	47
55	Finite element simulation of laser additive melting and solidification of Inconel 718 with experimentally tested thermal properties. <i>Finite Elements in Analysis and Design</i> , 2017 , 135, 36-43	2.2	44
54	Local shear stress-strain response of Sn-3.5Ag/Cu solder joint with high fraction of intermetallic compounds: Experimental analysis. <i>Journal of Alloys and Compounds</i> , 2016 , 680, 665-676	5.7	38
53	Miniaturization of Micro-Solder Bumps and Effect of IMC on Stress Distribution. <i>Journal of Electronic Materials</i> , 2016 , 45, 3683-3694	1.9	9
52	Investigating ultrasound imaging in the frequency domain for tissue characterisation. <i>Nondestructive Testing and Evaluation</i> , 2016 , 31, 209-218	2	5
51	Laser Additive Melting and Solidification of Inconel 718: Finite Element Simulation and Experiment. <i>Jom</i> , 2016 , 68, 967-977	2.1	37
50	Strength and Failure of Ultrafine Grain and Bimodal Al-Mg Alloy at High Temperatures. <i>Minerals, Metals and Materials Series</i> , 2016 , 279-282	0.3	
49	Multiscale Modeling of Novel Carbon Nanotube/Copper-Composite Material Used in Microelectronics. <i>Journal of Multiscale Modeling</i> , 2016 , 07, 1650001	0.8	1
48	Optimizing quality of additively manufactured Inconel 718 using powder bed laser melting process. <i>Additive Manufacturing</i> , 2016 , 11, 60-70	6.1	73
47	Single Crystal Plasticity Finite Element Analysis of Cu ₆ Sn ₅ Intermetallic. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2015 , 46, 1108-1118	2.3	10
46	Temperature distribution and melt geometry in laser and electron-beam melting processes [A comparison among common materials. <i>Additive Manufacturing</i> , 2015 , 8, 1-11	6.1	55

45	Copper-CNT Hybrid TSVs: Thermo-Mechanical Stresses and Reliability Analysis. <i>International Journal of High Speed Electronics and Systems</i> , 2015 , 24, 1550006	0.5	5
44	Representation of a microstructure with bimodal grain size distribution through crystal plasticity and cohesive interface modeling. <i>Mechanics of Materials</i> , 2015 , 82, 1-12	3.3	31
43	Local and Global Mechanical Behavior and Microstructure of Ti6Al4V Parts Built Using Electron Beam Melting Technology. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2015 , 46, 3835-3841	2.3	38
42	Effect of Intermetallic Compounds on the Thermomechanical Fatigue Life of Three-Dimensional Integrated Circuit Package Microsolder Bumps: Finite Element Analysis and Study. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2015 , 137,	2	19
41	Deformation and Failure of an Al-Mg Alloy Investigated through Multiscale Microstructural Models 2015 , 243-249		
40	Thermal Modeling of Laser Based Additive Manufacturing Processes within Common Materials. <i>Procedia Manufacturing</i> , 2015 , 1, 238-250	1.5	66
39	Mechanical integrity of a carbon nanotube/copper-based through-silicon via for 3D integrated circuits: a multi-scale modeling approach. <i>Nanotechnology</i> , 2015 , 26, 485705	3.4	10
38	Structural Size Effect on Mechanical Behavior of Intermetallic Material in Solder Joints: Experimental Investigation. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2015 , 137,	2	2
37	Deformation and Failure of an Al-Mg Alloy Investigated Through Multiscale Microstructural Models 2015 , 245-249		
36	Grain Growth Orientation and Anisotropy in Cu ₆ Sn ₅ Intermetallic: Nanoindentation and Electron Backscatter Diffraction Analysis. <i>Journal of Electronic Materials</i> , 2014 , 43, 996-1004	1.9	21
35	Finite element simulation of pile behaviour under thermo-mechanical loading in integral abutment bridges. <i>Structure and Infrastructure Engineering</i> , 2014 , 10, 643-653	2.9	7
34	Molecular Dynamics Simulation of Mechanical Interface Behavior of Copper and Single Walled Carbon Nanotube Bundles 2014 ,		2
33	Cohesive Zone Model for the Interface of Multiwalled Carbon Nanotubes and Copper: Molecular Dynamics Simulation. <i>Journal of Nanotechnology in Engineering and Medicine</i> , 2014 , 5,		10
32	Performance of piles in integral abutment bridges under thermo-mechanical cyclic loads. <i>Bridge Structures</i> , 2014 , 10, 11-17	0.7	2
31	Mechanical Anisotropy and Strain Rate Dependency Behavior of Ti6Al4V Produced Using E-Beam Additive Fabrication. <i>Journal of Engineering Materials and Technology, Transactions of the ASME</i> , 2014 , 136,	1.8	46
30	Effect of Varying Test Parameters on Elastic/Plastic Properties Extracted by Nanoindentation Tests. <i>Experimental Mechanics</i> , 2013 , 53, 1299-1309	2.6	5
29	Temperature dependency of mechanical behavior and strain rate sensitivity of an AlMg alloy with bimodal grain size. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2013 , 582, 276-283	5.3	14
28	Fatigue Crack Initiation and Propagation in Piles of Integral Abutment Bridges. <i>Computer-Aided Civil and Infrastructure Engineering</i> , 2013 , 28, 389-402	8.4	11

27	Mechanical Behavior of Ti-6Al-4V Manufactured by Electron Beam Additive Fabrication 2013 ,		7
26	Effect of Joint Size on Microstructure and Growth Kinetics of Intermetallic Compounds in Solid-Liquid Interdiffusion Sn3.5Ag/Cu-Substrate Solder Joints. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2013 , 135,	2	14
25	Fatigue Life of Piles in Integral-Abutment Bridges: Case Study. <i>Journal of Bridge Engineering</i> , 2013 , 18, 1105-1117	2.7	8
24	Interfacial Strength Between Single Wall Carbon Nanotubes and Copper Material: Molecular Dynamics Simulation. <i>Journal of Nanotechnology in Engineering and Medicine</i> , 2013 , 4,		10
23	Complete mechanical characterization of nanocrystalline AlMg alloy using nanoindentation. <i>Mechanics of Materials</i> , 2012 , 52, 1-11	3.3	22
22	Mechanical Strength and Failure Characterization of Sn-Ag-Cu Intermetallic Compound Joints at the Microscale. <i>Journal of Electronic Materials</i> , 2012 , 41, 573-579	1.9	4
21	Effects of tensile test parameters on the mechanical properties of a bimodal AlMg alloy. <i>Acta Materialia</i> , 2012 , 60, 5838-5849	8.4	47
20	IMC growth of Sn-3.5Ag/Cu system: Combined chemical reaction and diffusion mechanisms. <i>Journal of Alloys and Compounds</i> , 2012 , 537, 87-99	5.7	77
19	Fracture toughness of bonds using interfacial stresses in four-point bending test. <i>Mechanics of Materials</i> , 2011 , 43, 885-900	3.3	14
18	Fatigue and monotonic loading crack nucleation and propagation in bimodal grain size aluminum alloy. <i>Acta Materialia</i> , 2011 , 59, 3550-3570	8.4	33
17	Fatigue Crack Initiation and Propagation in Aileron Lever Using Successive-Initiation Modeling Approach. <i>Journal of Aircraft</i> , 2011 , 48, 1387-1395	1.6	3
16	Transition of Crack Propagation Path Under Varied Levels of Load in Bimodal Grain Size Al-Mg Alloy. <i>Journal of Engineering Materials and Technology, Transactions of the ASME</i> , 2011 , 133,	1.8	5
15	A Novel Piezo-Actuator-Sensor Micromachine for Mechanical Characterization of Micro-Specimens. <i>Micromachines</i> , 2010 , 1, 129-152	3.3	5
14	Stress analysis of 3-dimensional IC package as function of structural design parameters. <i>Microelectronic Engineering</i> , 2010 , 87, 1852-1860	2.5	13
13	Numerical analysis of thermo-mechanical reliability of through silicon vias (TSVs) and solder interconnects in 3-dimensional integrated circuits. <i>Microelectronic Engineering</i> , 2010 , 87, 208-215	2.5	71
12	Microstructure and mechanical strength of snag-based solid liquid inter-diffusion bonds for 3 dimensional integrated circuits. <i>Thin Solid Films</i> , 2010 , 518, 4948-4954	2.2	3
11	An anisotropic mechanical fatigue damage evolution model for Pb-free solder materials. <i>Mechanics of Materials</i> , 2009 , 41, 878-885	3.3	10
10	A meso-scale damage evolution model for cyclic fatigue of viscoplastic materials. <i>International Journal of Fatigue</i> , 2009 , 31, 703-711	5	23

9	Interaction Effect of Voids and Standoff Height on Thermomechanical Durability of BGA Solder Joints. <i>IEEE Transactions on Device and Materials Reliability</i> , 2009 , 9, 348-355	1.6	12
8	Effect of Selected Process Parameters on Durability and Defects in Surface-Mount Assemblies for Portable Electronics. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2008 , 31, 51-60		18
7	Reliability estimation for large-area solder joints using explicit modeling of damage. <i>IEEE Transactions on Device and Materials Reliability</i> , 2008 , 8, 375-386	1.6	15
6	Damage Initiation and Propagation in Voided Joints: Modeling and Experiment. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2008 , 130,	2	31
5	Estimating fatigue damage model constants with maximum likelihood method. <i>International Journal of Materials and Structural Integrity</i> , 2008 , 2, 164	0.3	
4	Effect of Voids on Thermomechanical Durability of Pb-Free BGA Solder Joints: Modeling and Simulation. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2007 , 129, 273-277	2	23
3	Implementation of Six Sigma quality system in Celestica with practical examples. <i>International Journal of Six Sigma and Competitive Advantage</i> , 2006 , 2, 69	1.6	4
2	Effect of Voids on Thermo-Mechanical Durability of Pb-Free BGA Solder Joints: Modeling and Simulation 2005 , 57		3
1	Strength and Failure of Ultrafine Grain and Bimodal Al-Mg Alloy at High Temperatures 277-282		